Unit: mm

TOSHIBA Schottky Barrier Rectifier Schottky Barrier Type

CUS02

Switching Mode Power Supply Applications Portable Equipment Battery Applications

- Forward voltage: $V_{FM} = 0.45 \text{ V@I}_F = 0.7 \text{ A}$
- Average forward current: IF(AV) = 1.0 A
- Repetitive peak reverse voltage: $V_{RRM} = 30 \text{ V}$
- Suitable for high-density board assembly due to the use of a small surface-mount package, US-FLATTM

Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Average forward current	I _{F (AV)}	1.0 (Note 1)	Α
Peak one cycle surge forward current (non-repetitive)	I _{FSM}	20 (50 Hz)	Α
Junction temperature	Tj	−40 to 150	°C
Storage temperature range	T _{stg}	-40 to 150	°C

Note 1: Ta = 52°C: Device mounted on a glass-epoxy board

> Board size: 50 mm × 50 mm, Land size: 6 mm × 6 mm

Rectangular waveform ($\alpha = 180^{\circ}$), $V_R = 15 \text{ V}$

Note 2: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

 $1.25 \, {}^{+\ 0.2}_{-\ 0.1}$ $0.13^{\,+\,0.05}_{\,-\,0.03}$ 0.88 ± 0.1 1.9 ± 0.1 2.5 ± 0.2 0.6 ± 0.1 0.88 ± 0.1 0.78 ± 0.1 1 ANODE 2 CATHODE 0.6 ± 0.1 **JEDEC JEITA** TOSHIBA 3-2B1A

Weight: 0.004 g (typ.)

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Electrical Characteristics (Ta = 25°C)

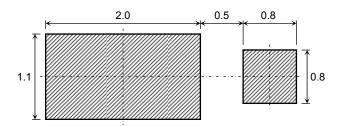
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Peak forward voltage	V _{FM (1)}	I _{FM} = 0.1 A	_	0.35	_		
	V _{FM (2)}	I _{FM} = 0.7 A	_	0.42	0.45	V	
	V _{FM (3)}	I _{FM} = 1.0 A	_	0.47	-		
Repetitive peak reverse current	I _{RRM (1)}	V _{RRM} = 5 V	_	0.7	ı	μA	
	I _{RRM (2)}	V _{RRM} = 30 V	_	10	100	μ	
Junction capacitance	Cj	V _R = 10 V, f = 1.0 MHz	_	40	ı	pF	
Thermal resistance (junction to ambient)		Device mounted on a ceramic board (soldering land: 2 mm × 2 mm)	_	_	75		
	R _{th (j-a)}	Device mounted on a glass-epoxy board (soldering land: 6 mm × 6 mm)	_	_	150	°C/W	
Thermal resistance (junction to lead)	R _{th (j-ℓ)}	Junction to lead of cathode side	_	_	30	°C/W	

Marking

Abbreviation Code	Part No.		
2	CUS02		

Standard Soldering Pad

Unit: mm



Handling Precaution

Schottky barrier diodes have reverse current characteristics compared to other diodes.

There is a possibility SBD may cause thermal runaway when it is used under high temperature or high voltage. Please take forward and reverse loss into consideration during design.

The absolute maximum ratings denote the absolute maximum ratings, which are rated values and must not be exceeded during operation, even for an instant. The following are the general derating methods that we recommend for designing a circuit using this device.

VRRM: Use this rating with reference to the above. VRRM has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.

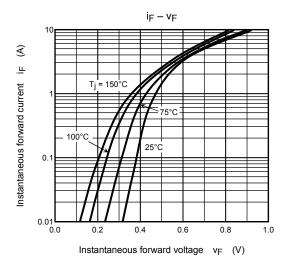
IF(AV): We recommend that the worst-case current be no greater than 80% of the absolute maximum rating of IF(AV) and T_j be below 120°C. When using this device, take the margin into consideration by using an allowable Ta max-IF(AV) curve.

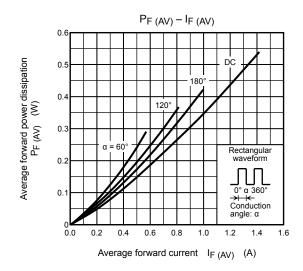
IFSM: This rating specifies the non-repetitive peak current. This is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.

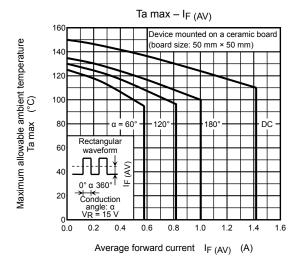
 T_j : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at T_j below 120°C.

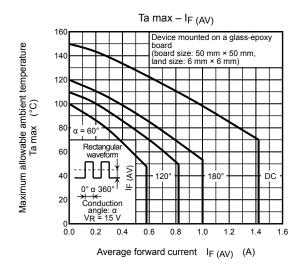
Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, design a circuit board and a soldering land size to match the appropriate thermal resistance value.

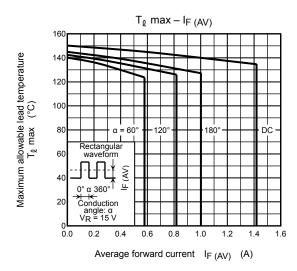
Refer to the Rectifiers databook for further information.

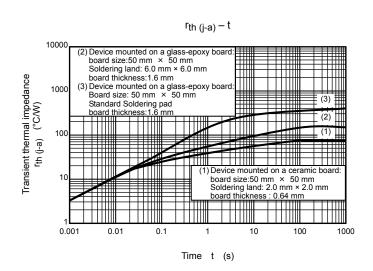




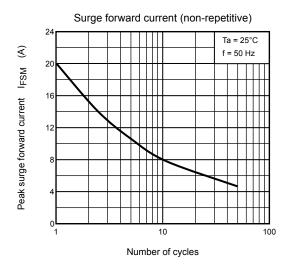


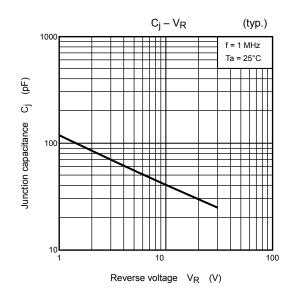


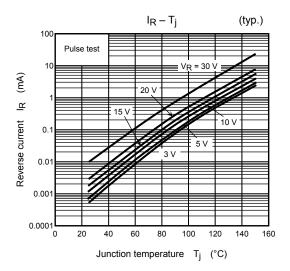


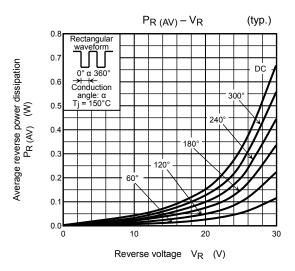


3 2008-05-13









RESTRICTIONS ON PRODUCT USE

20070701-EN GENERAL

- The information contained herein is subject to change without notice.
- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc.
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc.. Unintended Usage of TOSHIBA products listed in his document shall be made at the customer's own risk.
- The products described in this document shall not be used or embedded to any downstream products of which manufacture, use and/or sale are prohibited under any applicable laws and regulations.
- Please contact your sales representative for product-by-product details in this document regarding RoHS
 compatibility. Please use these products in this document in compliance with all applicable laws and regulations
 that regulate the inclusion or use of controlled substances. Toshiba assumes no liability for damage or losses
 occurring as a result of noncompliance with applicable laws and regulations.